



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	25-10-2023
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32L476MGY6MTR	52AQ*415CCC4	A	9965	25-10-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	14.33	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Tin/Silver/Copper/Nickel(SACN12505)	NAC	NAC		

Package Designator	Size	Nbr of instances	Shape	
WLCSP	Not applicable	81	No lead	
Comment	Package : A05Z WLCSP 81L DIE 415 P 0.4 MM DM00165935			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-14th June 2023				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	52AQ*415CCC4				8999999.0	1000024.8
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	10.197	mg	supplier	die	Silicon (Si)	7440-21-3		9.627	mg	944101	671667
				supplier	metallization	Aluminium (Al)	7429-90-5		0.027	mg	2648	1884
				supplier	metallization	Copper (Cu)	7440-50-8		0.242	mg	23732	16884
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	98	70
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.078	mg	7649	5442
				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	294	209
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	196	140
				supplier	Passivation	Silicon Nitride	12033-89-5		0.061	mg	5982	4256
				supplier	Passivation	Silicon Oxide	7631-86-9		0.156	mg	15299	10884
				Plating Seed layer 1	M-011 Other inorganic materials	0.012	mg	supplier	Alloy	Titanium (Ti)	7440-32-6	
Re-passivatipon layer	M-011 Other inorganic materials	0.104	mg	supplier	Alloy	Copper (Cu)	7440-50-8		0.010	mg	799037	675
				supplier	Polymer	4-Butyrolactone	96-48-0		0.094	mg	900000	6558
				supplier	Polymer	1-Methoxy-2-propyl acetate	108-65-6		0.010	mg	100000	729
Redistribution Layer	M-011 Other inorganic materials	0.266	mg	supplier	Alloy	Copper (Cu)	7440-50-8		0.266	mg	1000000	18561
Plating Seed layer 2	M-011 Other inorganic materials	0.007	mg	supplier	Alloy	Titanium (Ti)	7440-32-6		0.001	mg	200963	94
				supplier	Alloy	Copper (Cu)	7440-50-8		0.005	mg	799037	372
Re-passivatipon layer	M-011 Other inorganic materials	0.086	mg	supplier	Polymer	4-Butyrolactone	96-48-0		0.078	mg	900000	5410
				supplier	Polymer	1-Methoxy-2-propyl acetate	108-65-6		0.009	mg	100000	601
UBM	M-011 Other inorganic materials	0.229	mg	supplier	Alloy	Copper (Cu)	7440-50-8		0.229	mg	1000000	15998
Solder ball	Solder	2.995	mg	supplier	Solder	Tin (Sn)	7440-31-5		2.942	mg	982500	205272
				supplier	Solder	Silver (Ag)	7440-22-4		0.036	mg	12000	2507
				supplier	Solder	Copper (Cu)	7440-50-8		0.015	mg	5000	1045
				supplier	Solder	Nickel (Ni)	7440-02-0		0.001	mg	500	104
Back Side Coating	M-011 Other inorganic materials	0.437	mg	supplier	Polymer	Polybutylene terephthalate (PBT)	25038-59-9		0.284	mg	650000	19821
				supplier	Polymer	Silica	Proprietary		0.085	mg	195000	5946
				supplier	Polymer	Proprietary Material-Other Epoxy resins	Proprietary		0.033	mg	75000	2287
				supplier	Polymer	Proprietary Material-Other Acrylic resins	Proprietary		0.033	mg	75000	2287
				supplier	Polymer	Carbon black	1333-86-4		0.002	mg	5000	152